



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4299GM V33		<b>Issued</b>		23. January 2018		
<b>MA#</b>		MA001719090						
<b>Package</b>		PG-DSO-14-30		<b>Weight*</b>		143.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.584	2.50	2.50	24997	24997
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		421	
	non noble metal	iron	7439-89-6	1.207	0.84		8418	
wire	non noble metal	copper	7440-50-8	49.007	34.18	35.07	341811	350755
	noble metal	gold	7440-57-5	0.301	0.21	0.21	2100	2100
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1191
plastics		epoxy resin	-	7.852	5.48		54767	
	inorganic material	silicondioxide	60676-86-0	77.327	53.93	59.53	539337	595295
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8552	8552
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7182	7182
glue	plastics	acrylic resin	-	0.351	0.24		2446	
	noble metal	silver	7440-22-4	1.243	0.87	1.11	8673	11119
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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